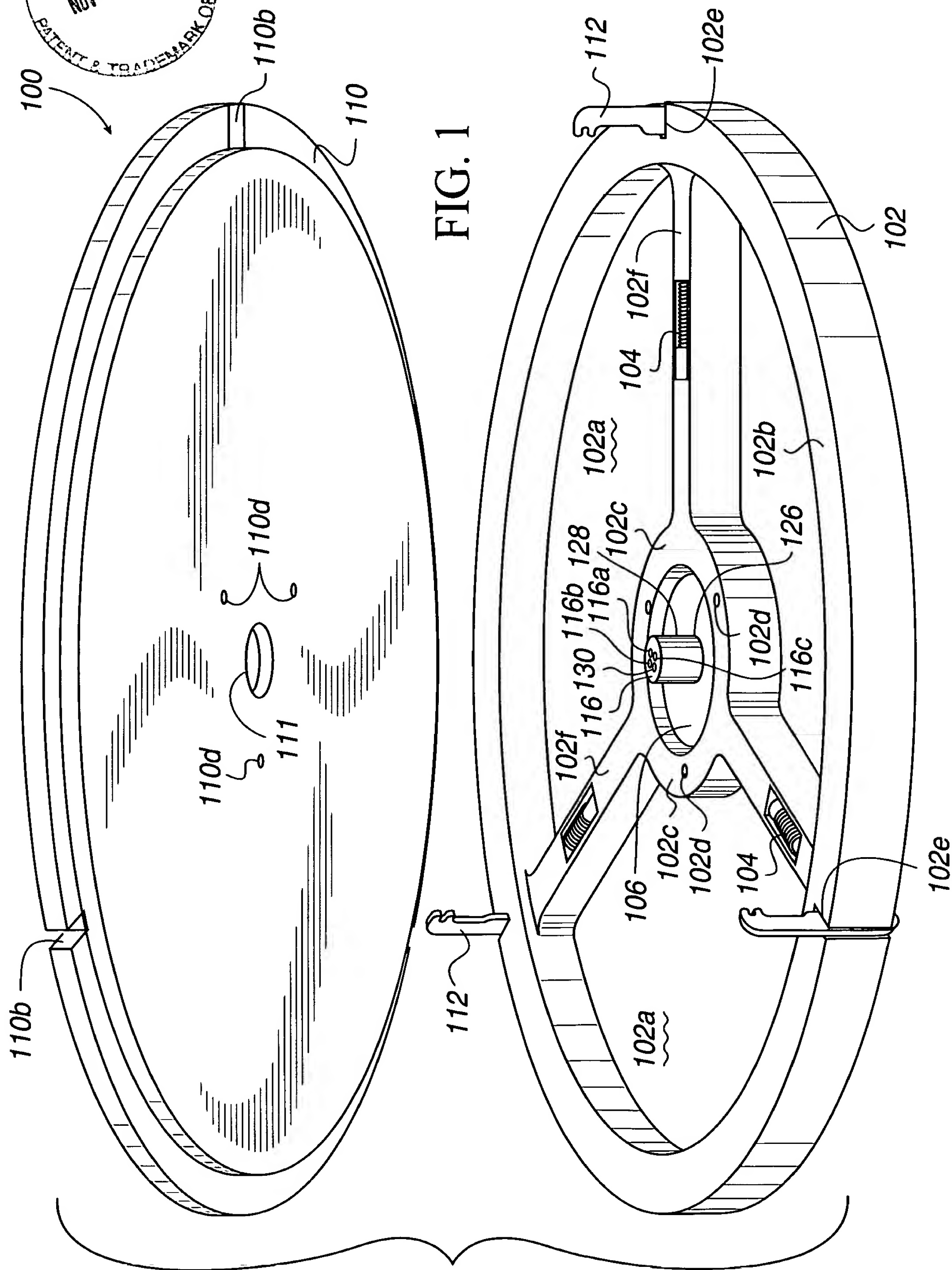
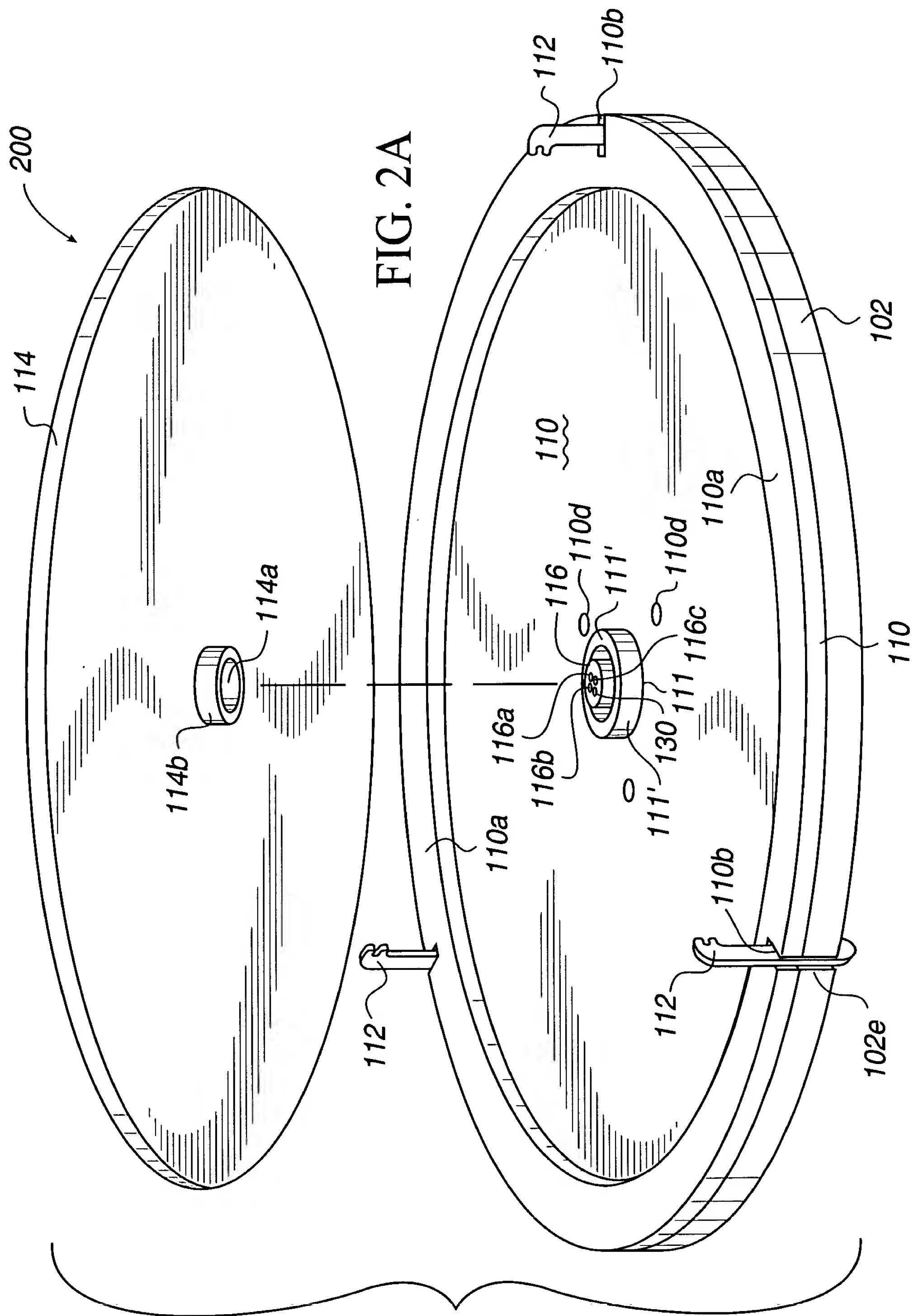
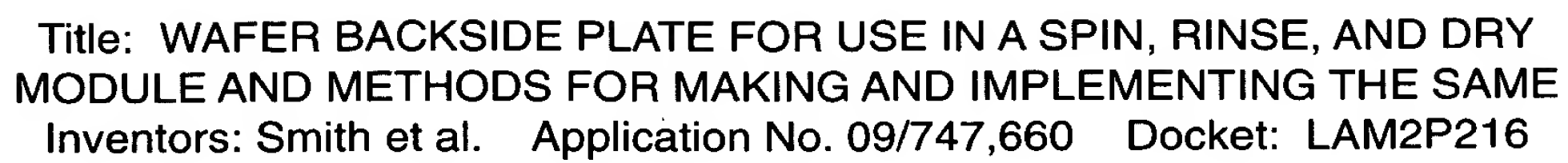
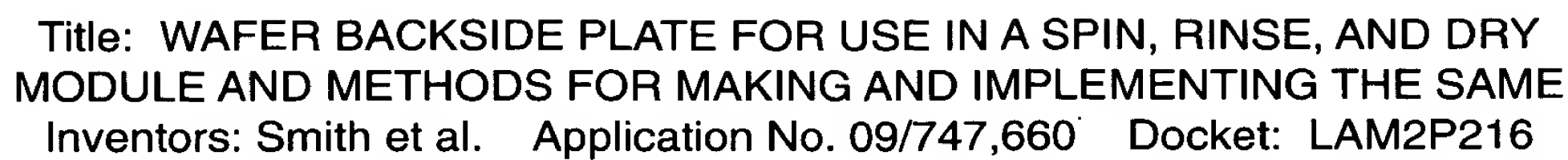
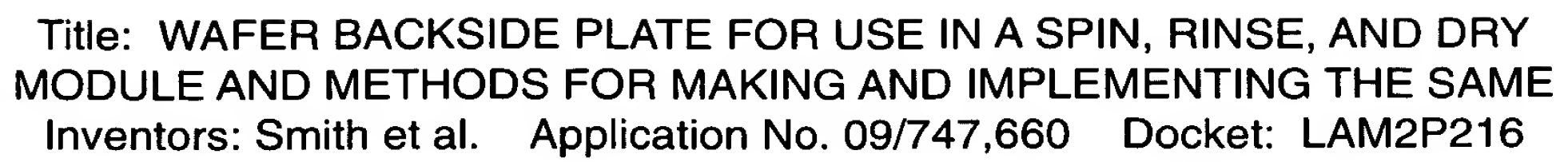


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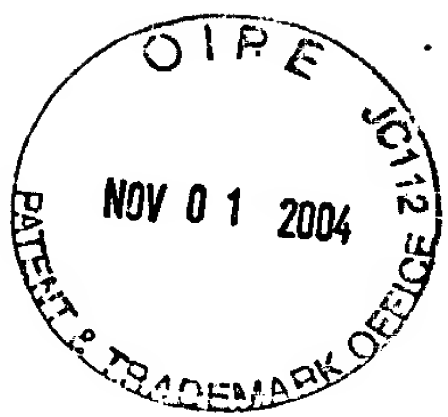






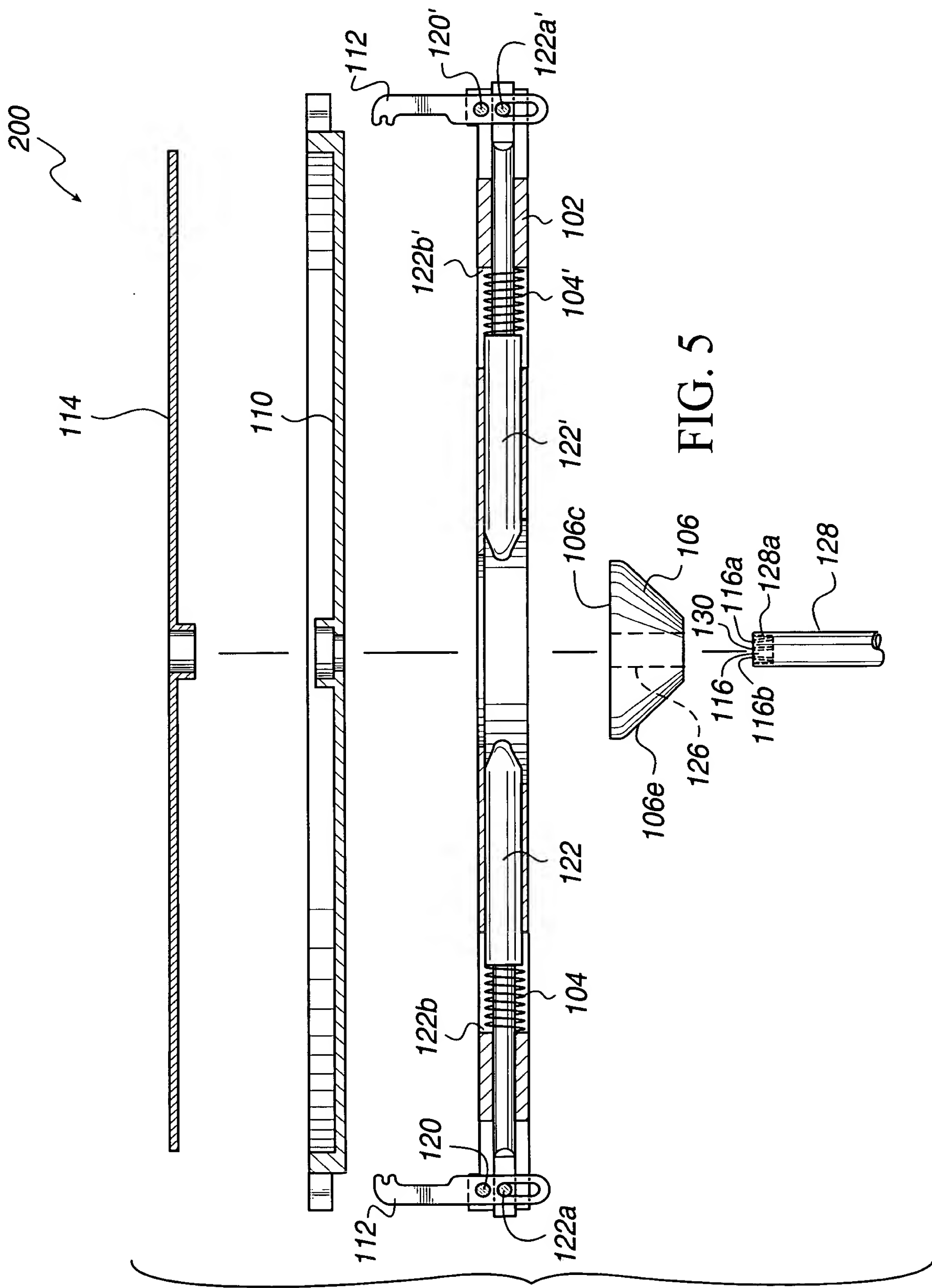
This cross-sectional view shows a mechanical assembly. A base member 110 is shown with a top surface 110a and a bottom surface 110b. A component 112 is positioned on top of the base member 110, with a top surface 112a and a bottom surface 112b. A component 113 is positioned on top of component 112. A component 114 is positioned on top of component 110. A component 116 is positioned on top of component 110. A component 117 is positioned on top of component 116. A component 118 is positioned on top of component 110. A component 120 is positioned on top of component 110. A component 122 is positioned on top of component 110. A component 122a is positioned on top of component 122. A component 122b is positioned on top of component 122. A component 122c is positioned on top of component 122. A component 122d is positioned on top of component 122. A component 122e is positioned on top of component 122. A component 122f is positioned on top of component 122. A component 126 is positioned on top of component 122. A component 128 is positioned on top of component 126. A component 130 is positioned on top of component 128.

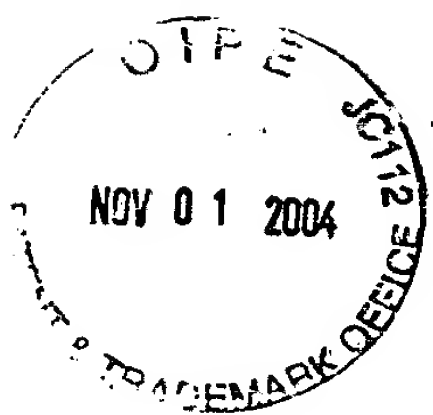
FIG. 4



Title: WAFER BACKSIDE PLATE FOR USE IN A SPIN, RINSE, AND DRY  
MODULE AND METHODS FOR MAKING AND IMPLEMENTING THE SAME  
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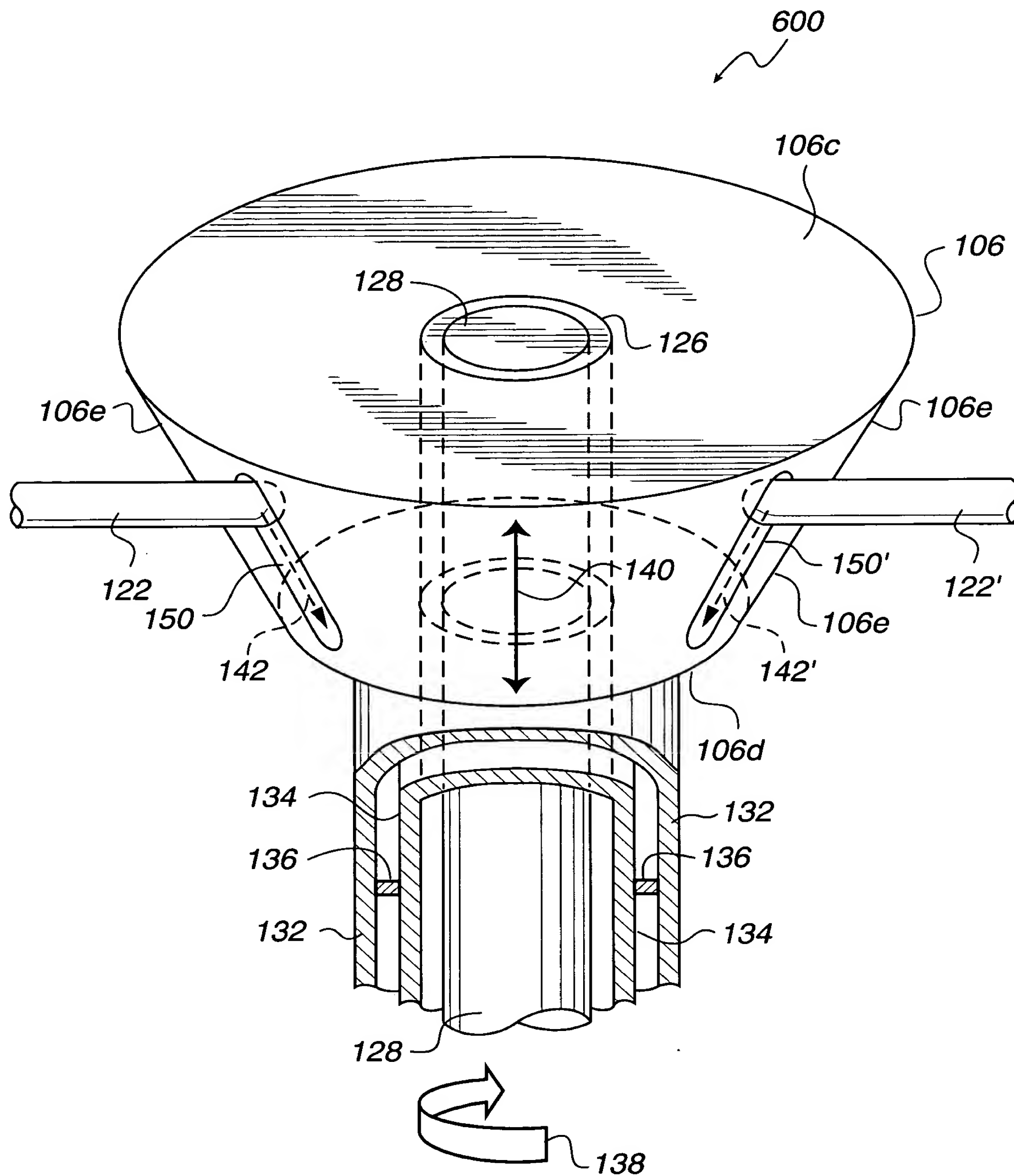
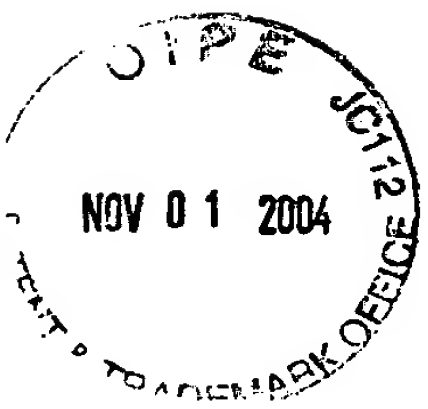


FIG. 6A



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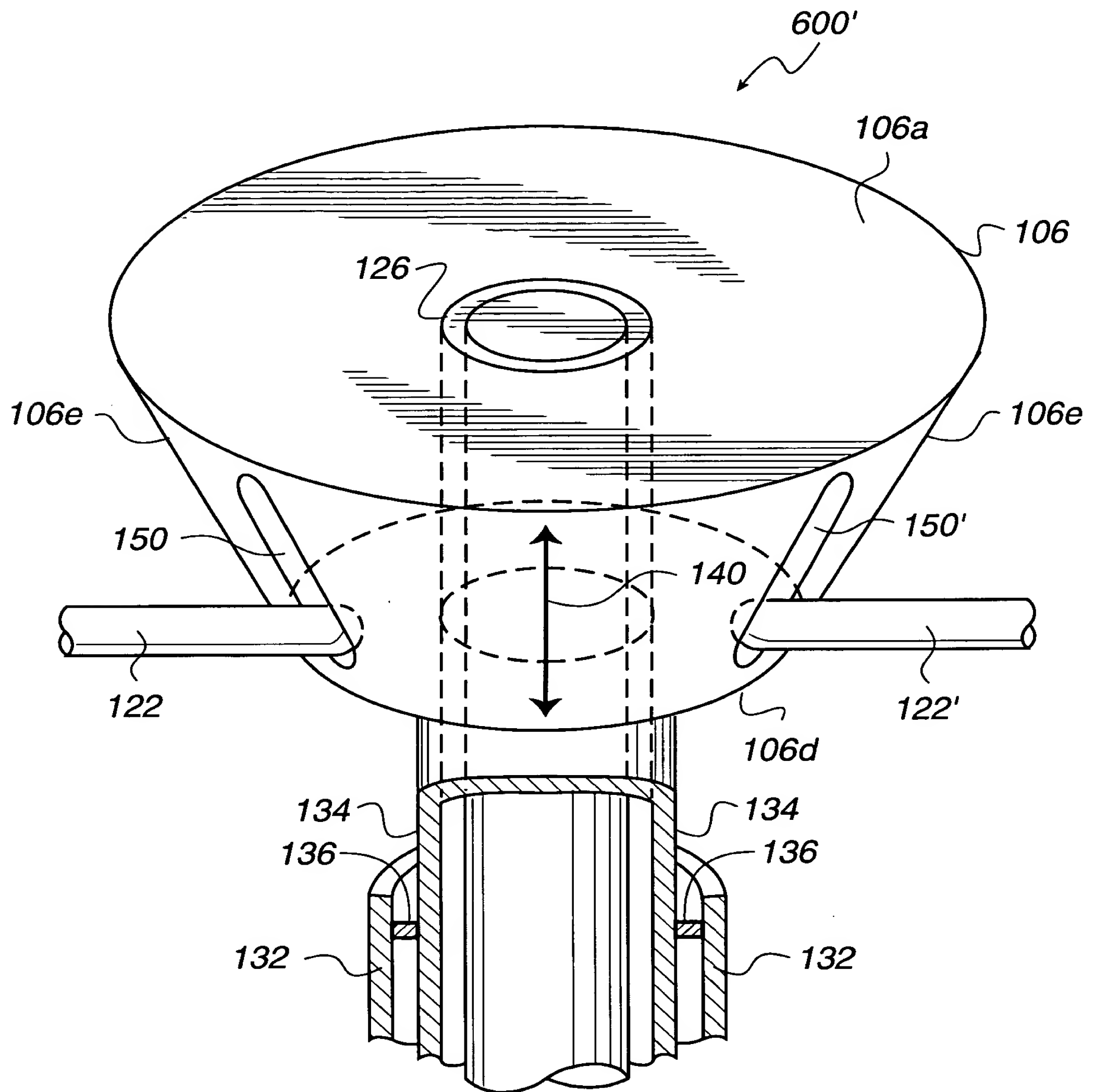


FIG. 6B

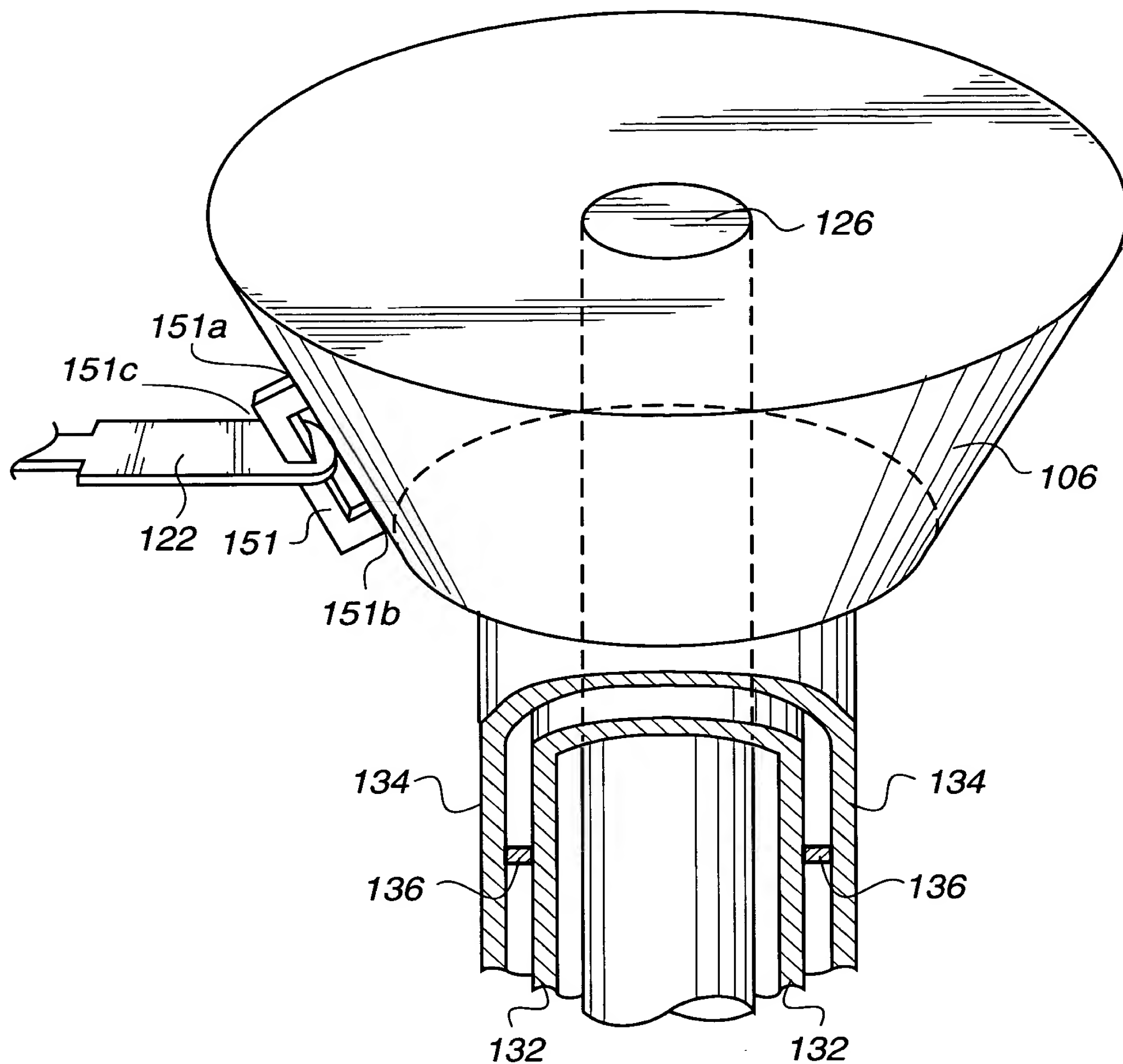


FIG. 6C



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FIG. 7A

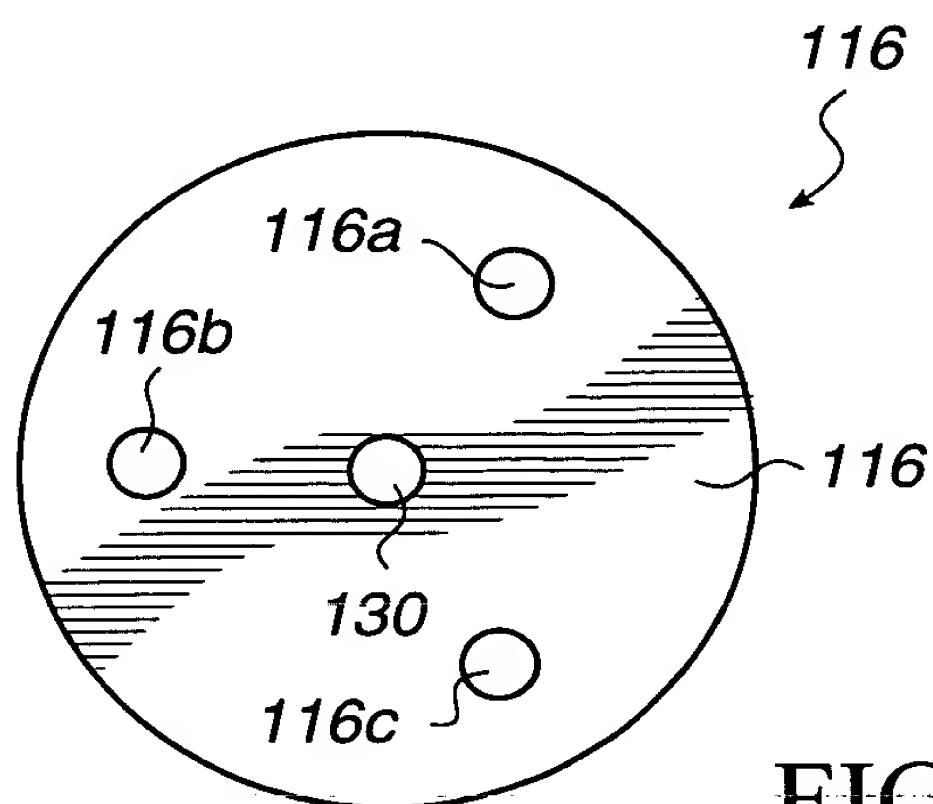
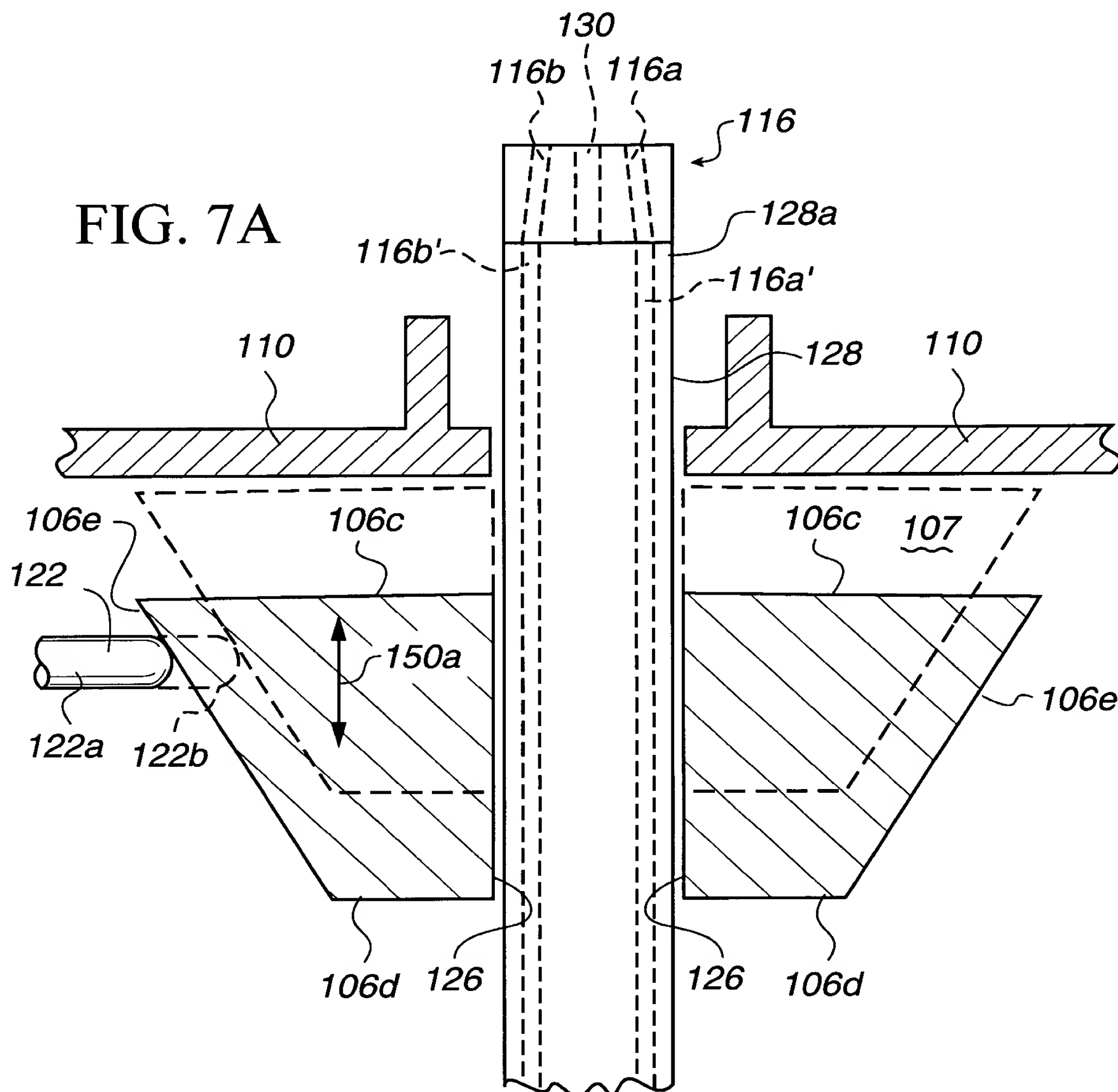
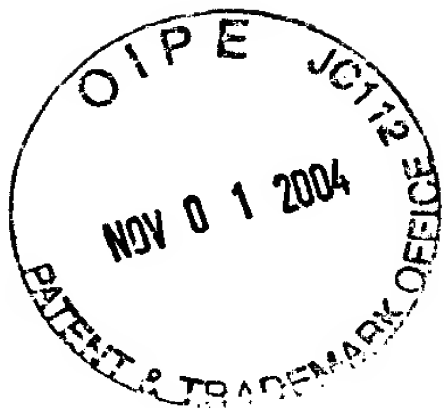


FIG. 7B



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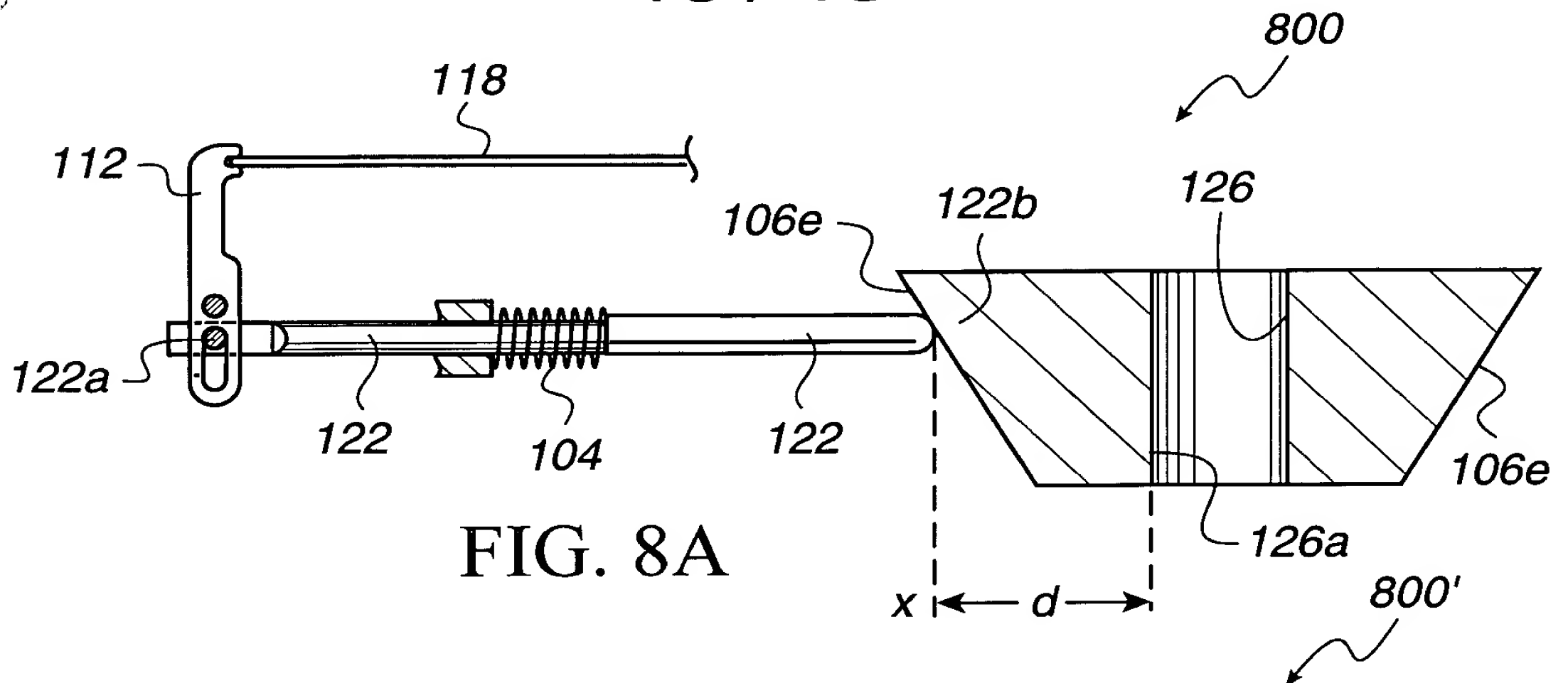


FIG. 8A

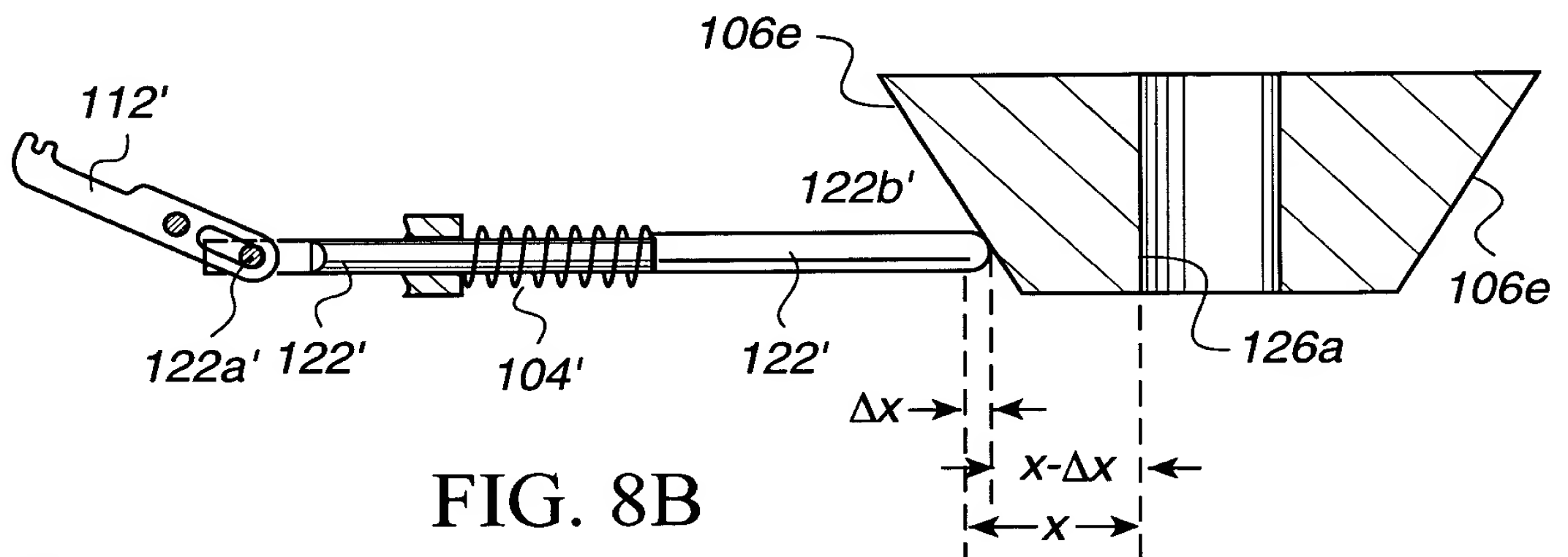


FIG. 8B

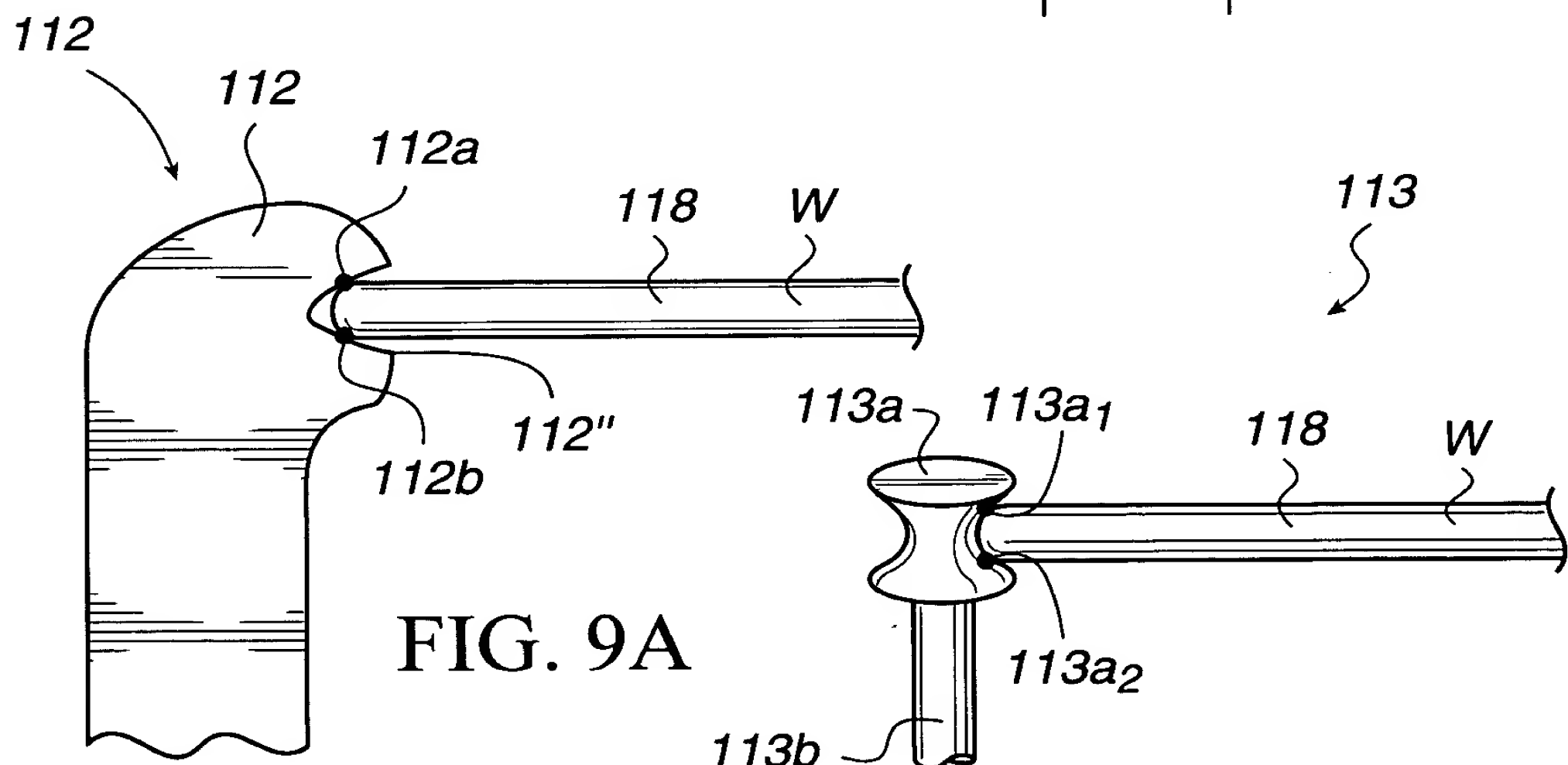


FIG. 9A

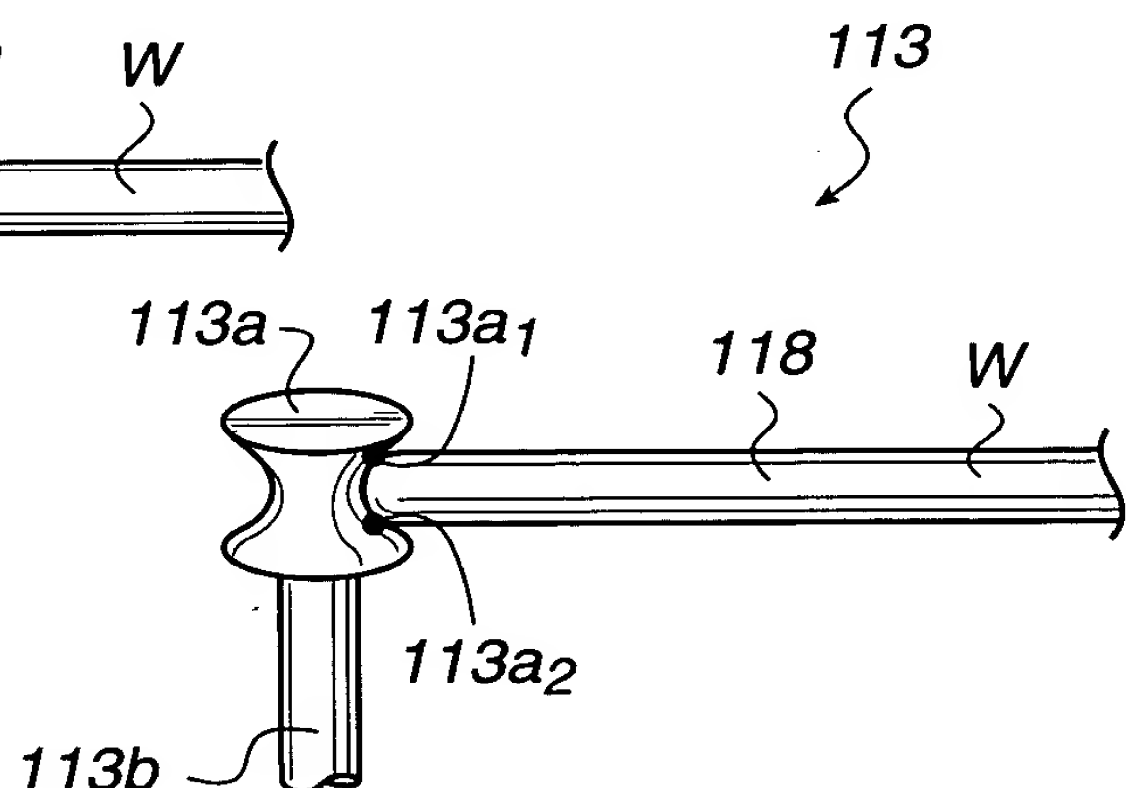
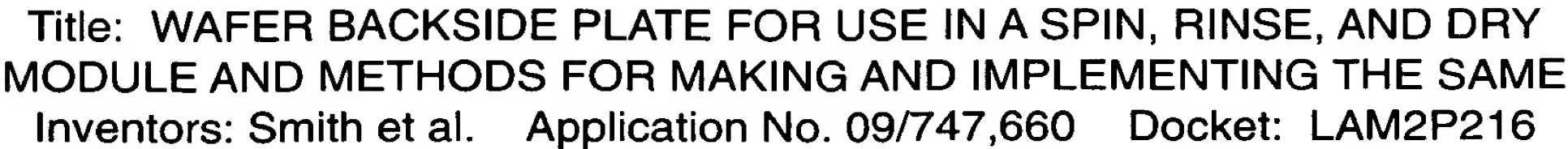
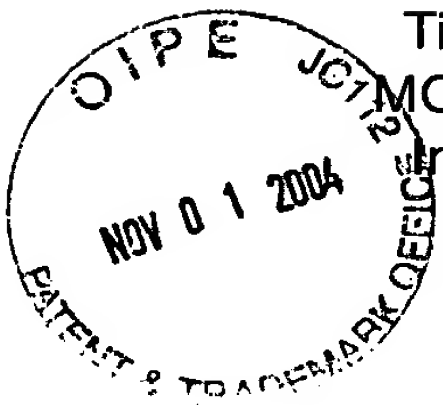


FIG. 9B





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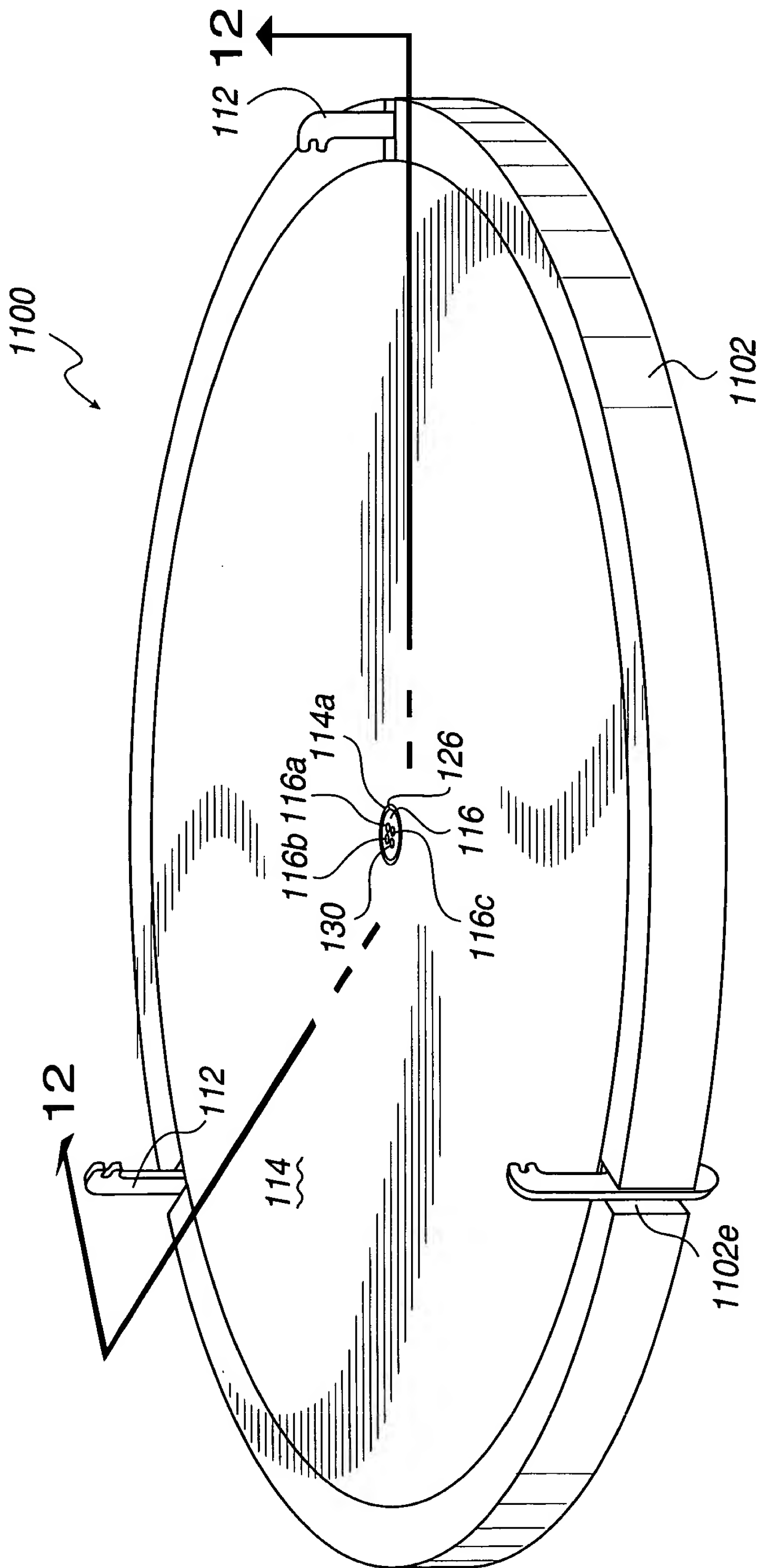
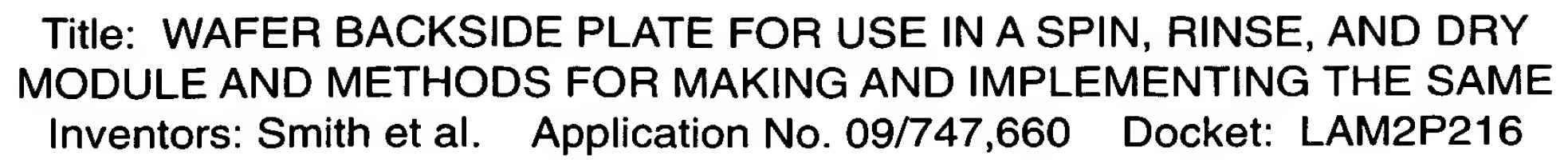
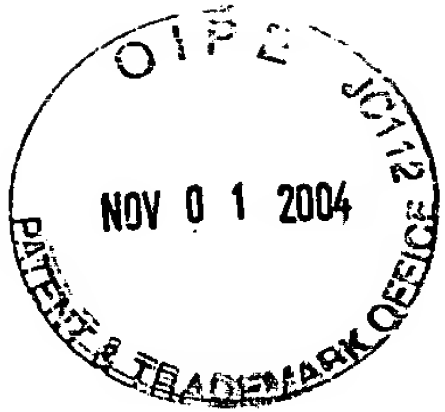


FIG. 11





Title: WAFER BACKSIDE PLATE FOR USE IN A SPIN, RINSE, AND DRY  
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Inventors: Smith et al. Application No. 09/747,660 Docket: LAM2P216

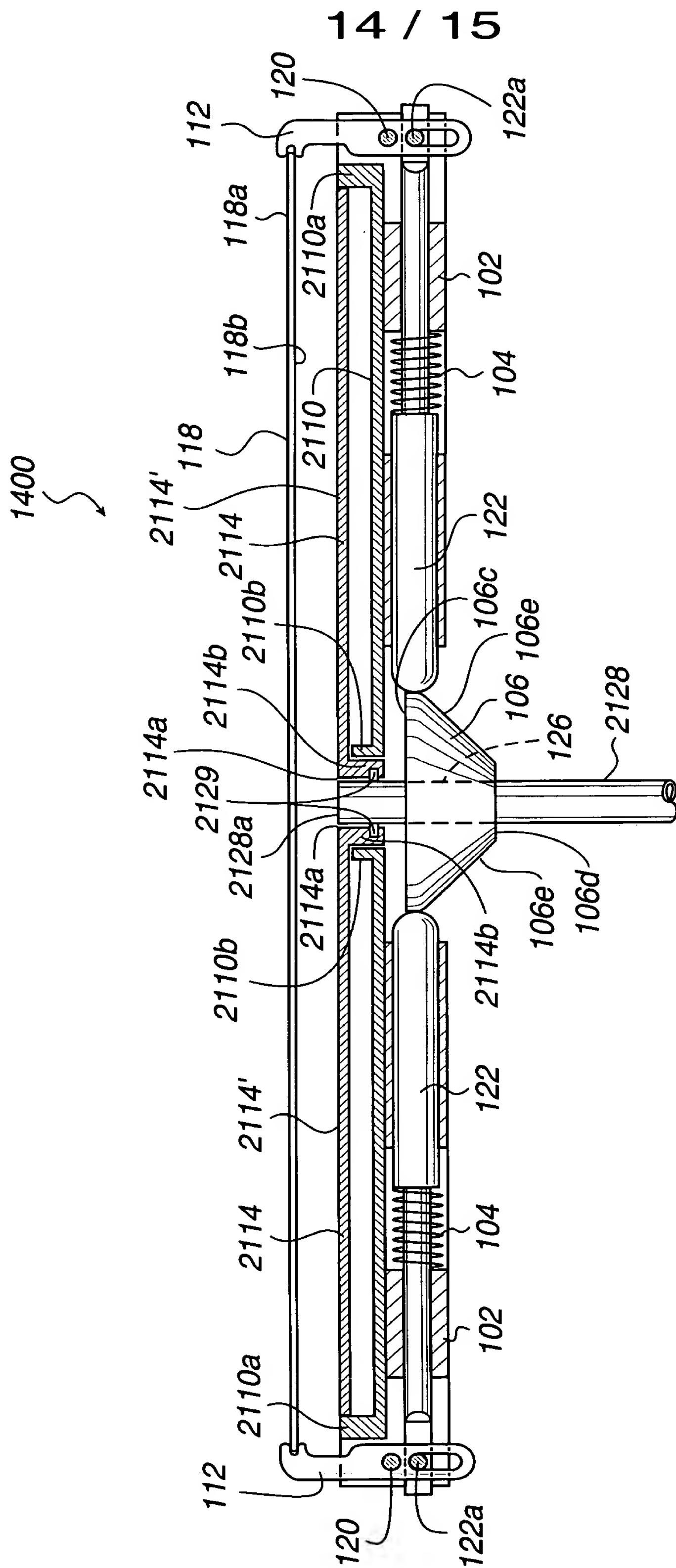
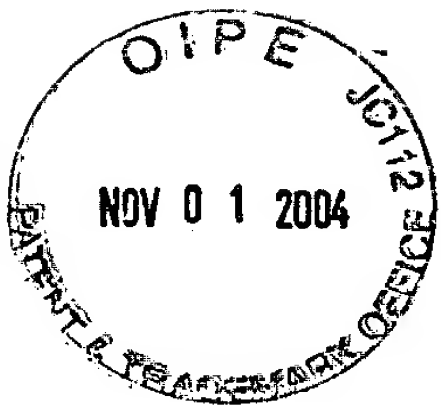


FIG. 14



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MODULE AND METHODS FOR MAKING AND IMPLEMENTING THE SAME  
Inventors: Smith et al. Application No. 09/747,660 Docket: LAM2P216

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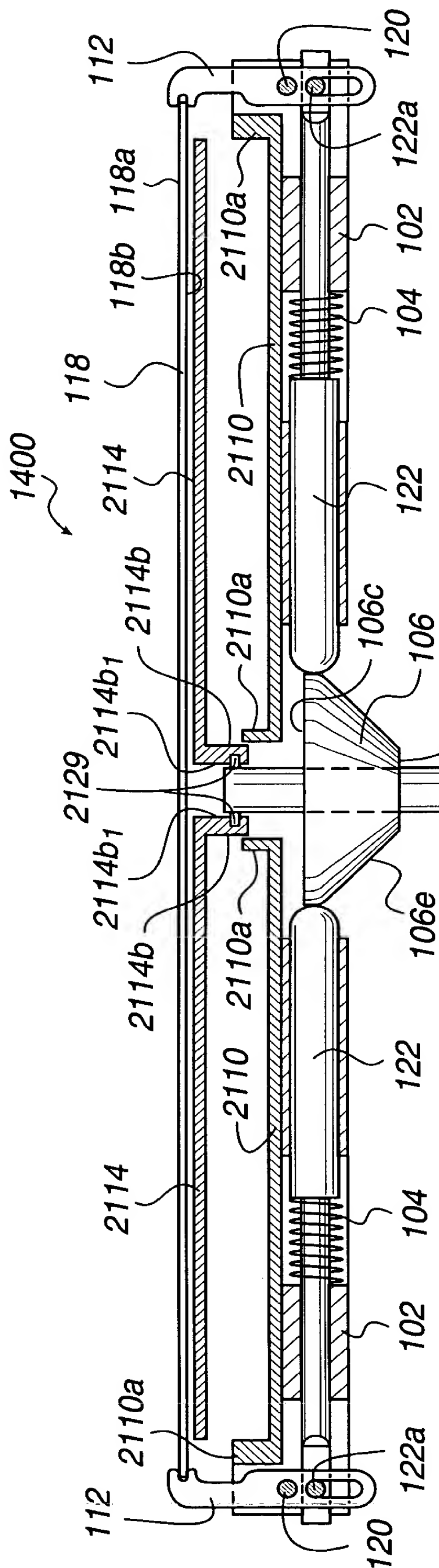


FIG. 15

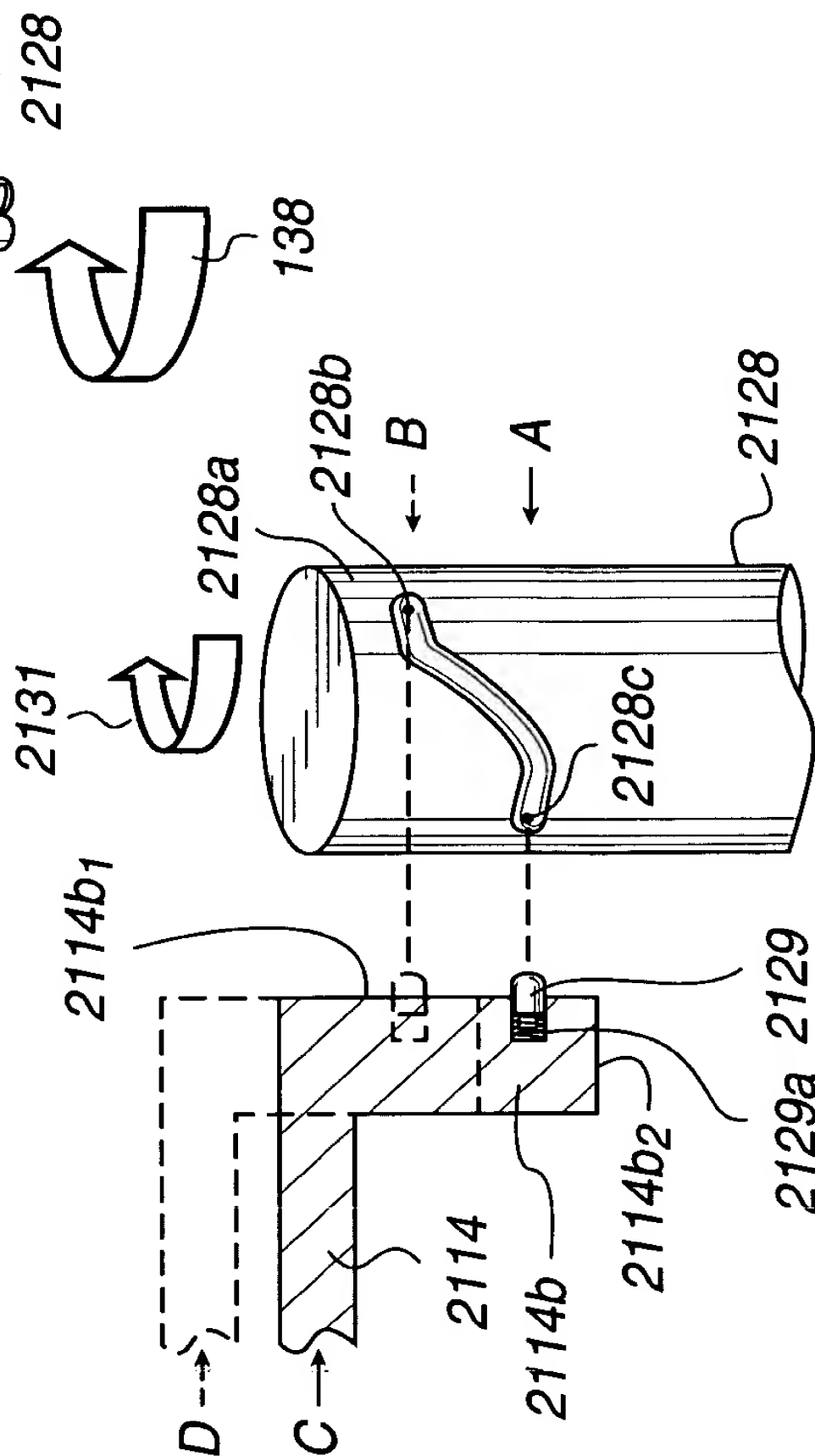


FIG. 16